

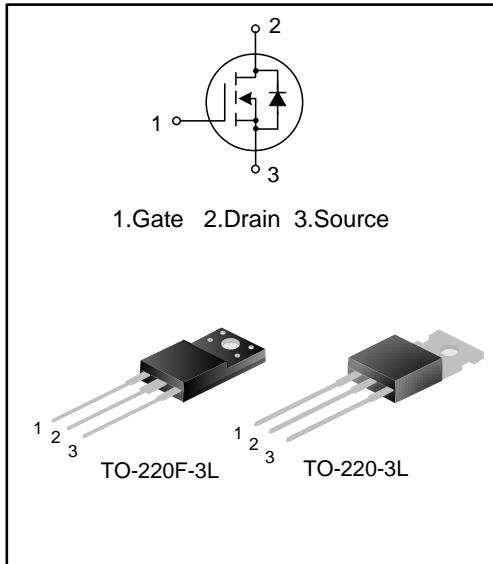
11A, 650V N-CHANNEL MOSFET

GENERAL DESCRIPTION

The SVF11N65T/F is an N-channel enhancement mode power MOS field effect transistor which is produced using Silan proprietary F-Cell™ structure VDMOS technology. The improved planar stripe cell and the improved guard ring terminal have been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are widely used in AC-DC power suppliers, DC-DC converters and H-bridge PWM motor drivers.

FEATURES

- ◆ 11A, 650V, $R_{DS(on)(typ.)} = 0.76\Omega$ @ $V_{GS}=10V$
- ◆ Low gate charge
- ◆ Low Crss
- ◆ Fast switching
- ◆ Improved dv/dt capability



ORDERING INFORMATION

Part No.	Package	Marking	Hazardous Substance Control	Packing Type
SVF11N65T	TO-220-3L	SVF11N65T	Pb free	Tube
SVF11N65F	TO-220F-3L	SVF11N65F	Pb free	Tube



ABSOLUTE MAXIMUM RATINGS ($T_c=25^\circ\text{C}$, UNLESS OTHERWISE NOTED)

Characteristics	Symbol	Ratings		Unit
		SVF11N65T	SVF11N65F	
Drain-Source Voltage	V_{DS}	650		V
Gate-Source Voltage	V_{GS}	± 30		V
Drain Current	I_D	11		A
		6.96		
Drain Current Pulsed	I_{DM}	44		A
Power Dissipation($T_c=25^\circ\text{C}$) - Derate above 25°C	P_D	205	47	W
		1.64	0.38	W/ $^\circ\text{C}$
Single Pulsed Avalanche Energy (Note 1)	E_{AS}	790		mJ
Operation Junction Temperature Rating	T_J	-55~+150		$^\circ\text{C}$
Storage Temperature Rating	T_{stg}	-55~+150		$^\circ\text{C}$

THERMAL CHARACTERISTICS

Characteristics	Symbol	Ratings		Unit
		SVF11N65T	SVF11N65F	
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	0.61	2.66	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	62.5	120	$^\circ\text{C}/\text{W}$

ELECTRICAL CHARACTERISTICS ($T_c=25^\circ\text{C}$ UNLESS OTHERWISE NOTED)

Characteristics	Symbol	Test conditions	Min.	Typ.	Max.	Unit
Drain –Source Breakdown Voltage	B_{VDSS}	$V_{GS}=0\text{V}$, $I_D=250\mu\text{A}$	650	--	--	V
Drain-Source Leakage Current	I_{DSS}	$V_{DS}=650\text{V}$, $V_{GS}=0\text{V}$	--	--	1.0	μA
Gate-Source Leakage Current	I_{GSS}	$V_{GS}=\pm 30\text{V}$, $V_{DS}=0\text{V}$	--	--	± 100	nA
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{GS}=V_{DS}$, $I_D=250\mu\text{A}$	2.0	--	4.0	V
On State Resistance	$R_{DS(on)}$	$V_{GS}=10\text{V}$, $I_D=5.5\text{A}$	--	0.76	0.84	Ω
Input Capacitance	C_{iss}	$V_{DS}=25\text{V}$, $V_{GS}=0\text{V}$, $f=1.0\text{MHZ}$	--	1354	--	pF
Output Capacitance	C_{oss}		--	152	--	
Reverse Transfer Capacitance	C_{rss}		--	5.3	--	
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=325\text{V}$, $I_D=11\text{A}$, $R_G=25\Omega$	--	21.32	--	ns
Turn-on Rise Time	t_r		--	34.51	--	
Turn-off Delay Time	$t_{d(off)}$		--	78.69	--	
Turn-off Fall Time	t_f		--	38.81	--	
Total Gate Charge	Q_g	$V_{DS}=520\text{V}$, $I_D=11\text{A}$, $V_{GS}=10\text{V}$	--	26.9	--	nC
Gate-Source Charge	Q_{gs}		--	7.67	--	
Gate-Drain Charge	Q_{gd}		--	9.21	--	



SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS

Characteristics	Symbol	Test conditions	Min.	Typ.	Max.	Unit
Continuous Source Current	I _S	Integral Reverse P-N Junction Diode in the MOSFET	--	--	11	A
Pulsed Source Current	I _{SM}		--	--	44	
Diode Forward Voltage	V _{SD}	I _S =11A, V _{GS} =0V	--	--	1.4	V
Reverse Recovery Time	T _{rr}	I _S =11A, V _{GS} =0V, dI _F /dt=100A/μS (Note 2)	--	518	--	ns
Reverse Recovery Charge	Q _{rr}		--	4.26	--	μC

Notes:

1. L=30mH, I_{AS}=6.75A, V_{DD}=100V, R_G=25Ω, starting T_J=25°C;
2. Pulse Test: Pulse width ≤300μs,Duty cycle≤2%;
3. Essentially independent of operating temperature.



TYPICAL CHARACTERISTICS

Figure 1. On-Region Characteristics

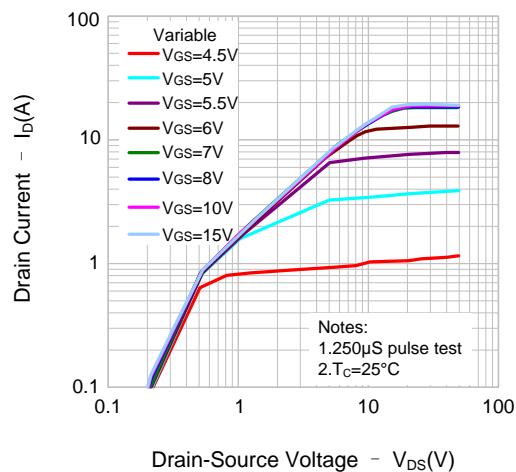


Figure 2. Transfer Characteristics

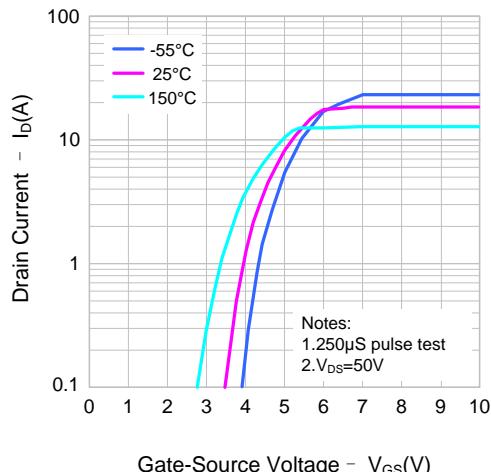


Figure 3. On-Resistance Variation vs.
Drain Current and Gate Voltage

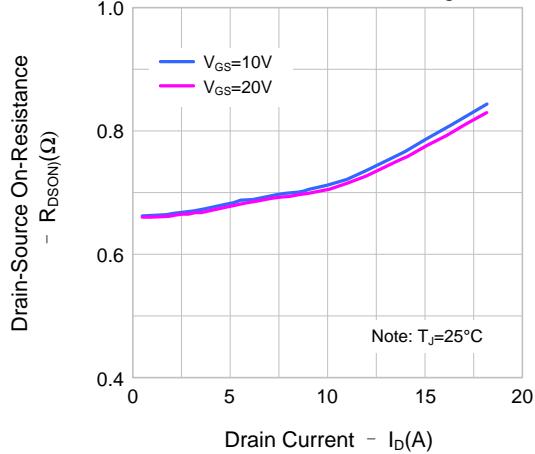


Figure 4. Body Diode Forward Voltage
Variation vs. Source Current and Temperature

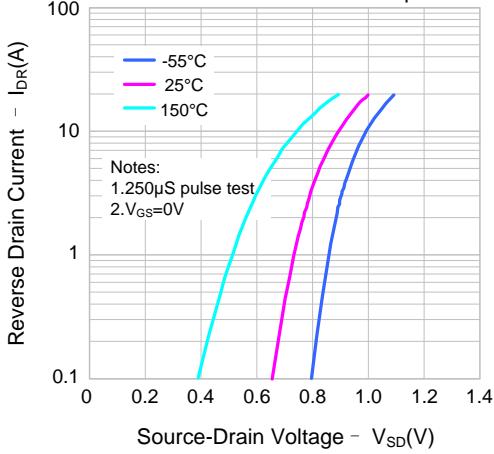


Figure 5. Capacitance Characteristics

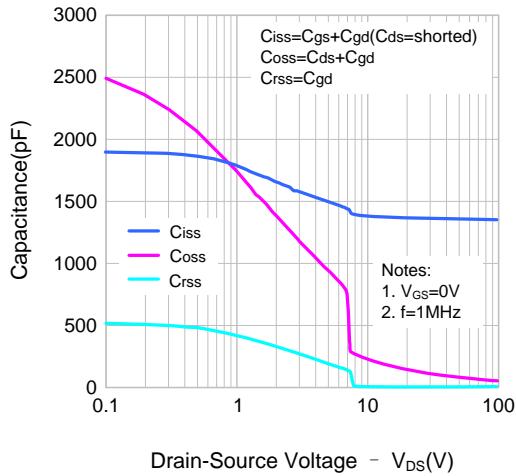
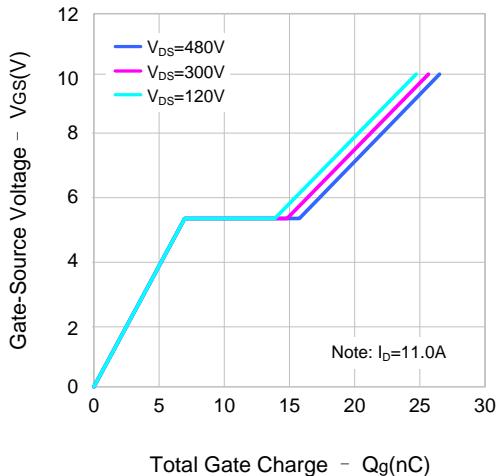


Figure 6. Gate Charge Characteristics





TYPICAL CHARACTERISTICS(CONTINUED)

Figure 7. Breakdown Voltage Variation vs. Temperature

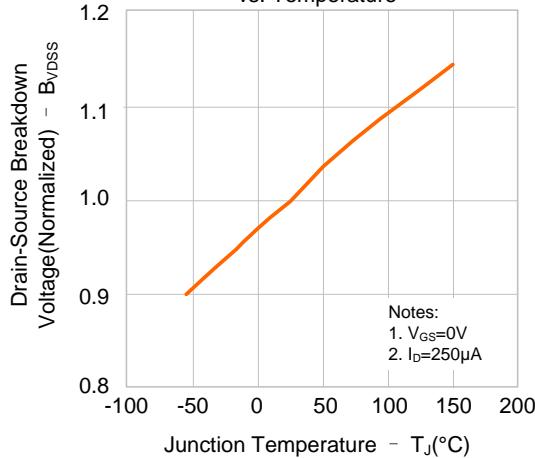


Figure 9-1. Max. Safe Operating Area (SVF11N65T)

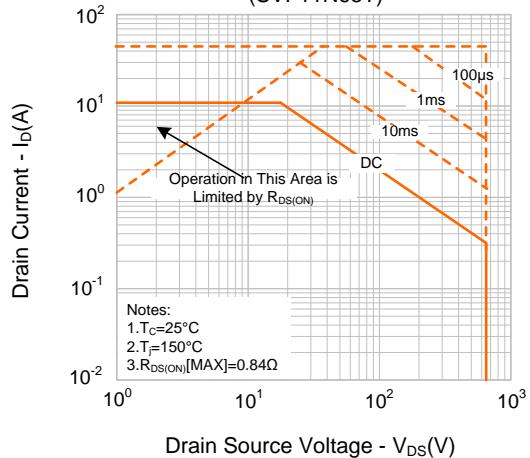


Figure 8. On-resistance Variation vs. Temperature

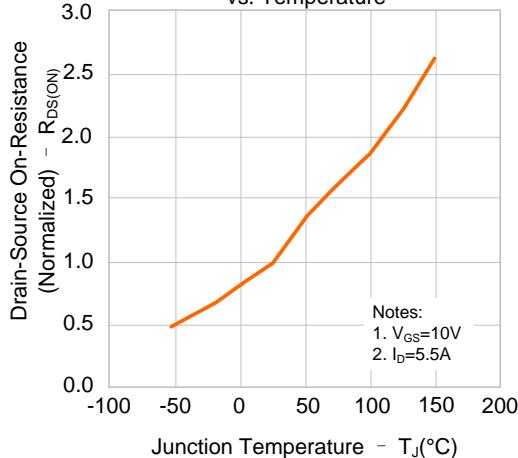


Figure 9-2. Max. Safe Operating Area (SVF11N65F)

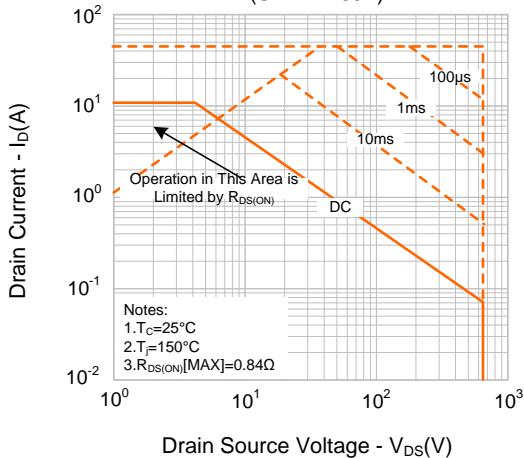
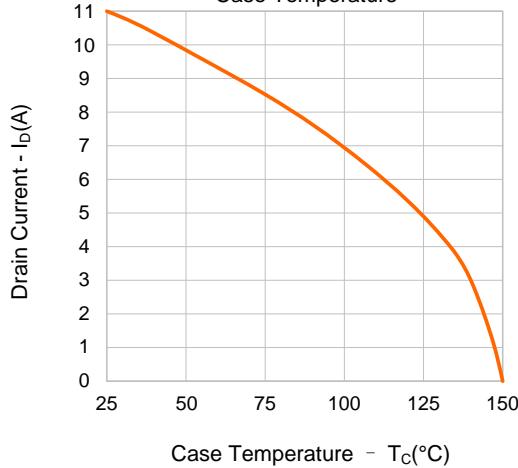


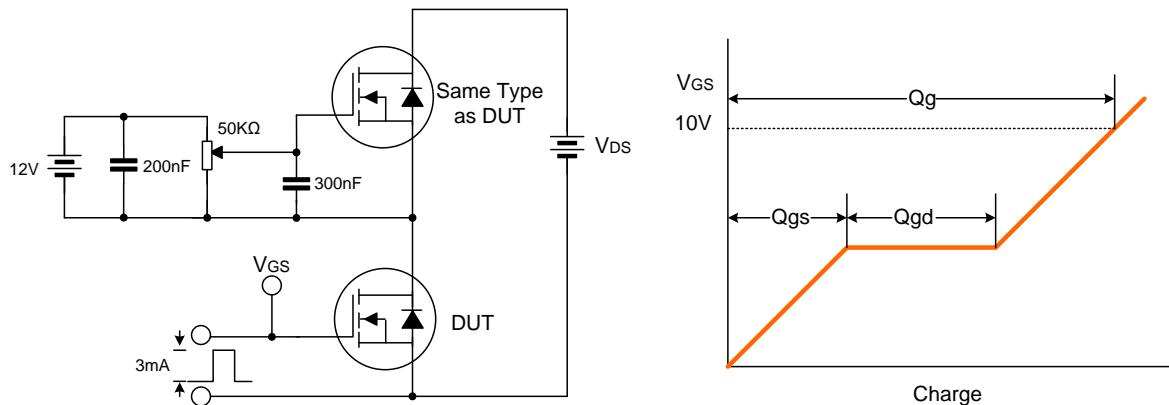
Figure 10. Maximum Drain Current vs. Case Temperature



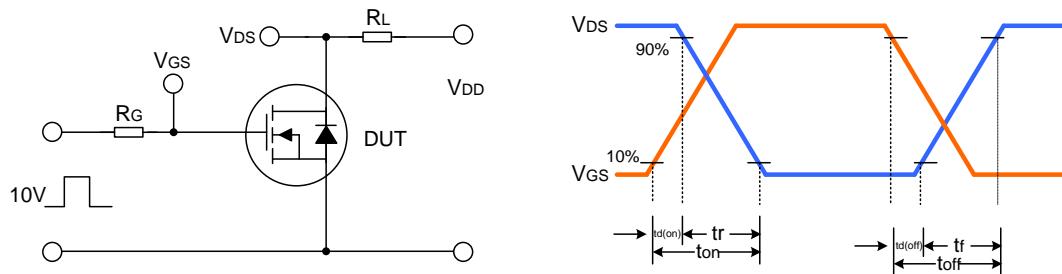


TYPICAL TEST CIRCUIT

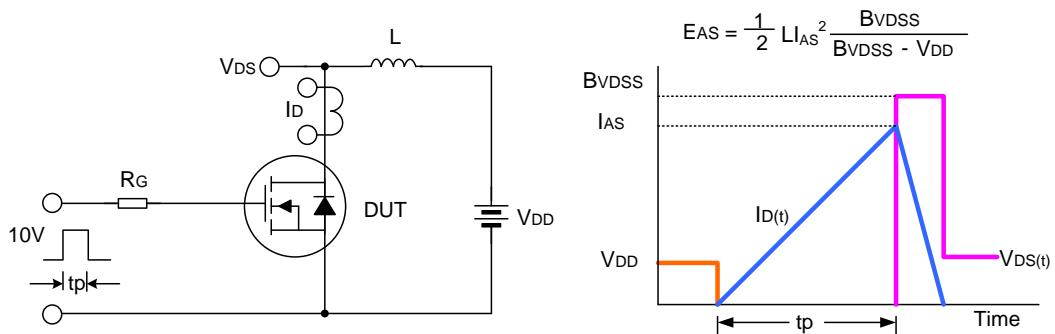
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveform



Unclamped Inductive Switching Test Circuit & Waveform

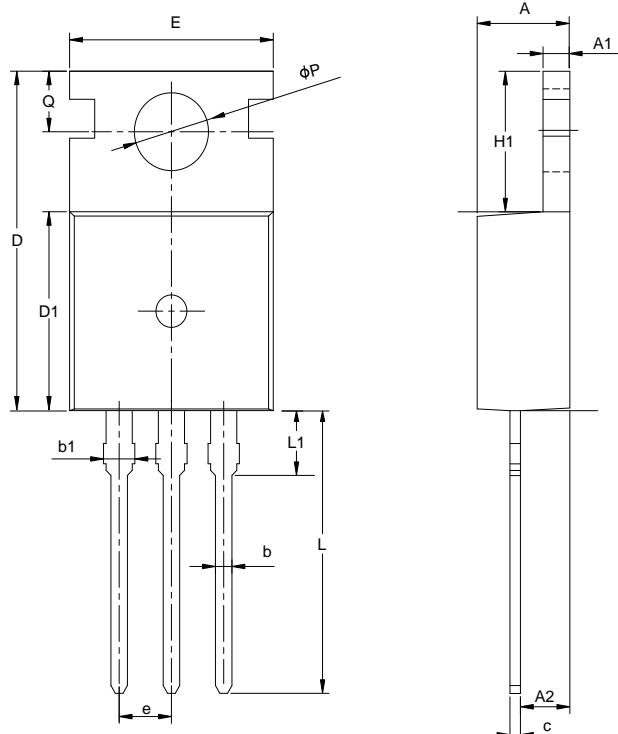




PACKAGE OUTLINE

TO-220-3L

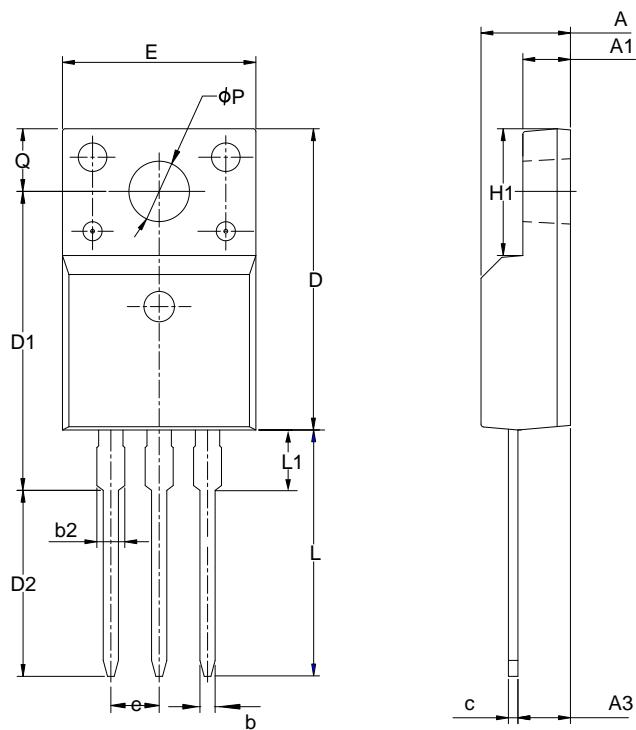
UNIT: mm



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	4.30	4.50	4.70
A1	1.00	1.30	1.50
A2	1.80	2.40	2.80
b	0.60	0.80	1.00
b1	1.00	—	1.60
c	0.30	—	0.70
D	15.10	15.70	16.10
D1	8.10	9.20	10.00
E	9.60	9.90	10.40
e	2.54BSC		
H1	6.10	6.50	7.00
L	12.60	13.08	13.60
L1	—	—	3.95
φP	3.40	3.70	3.90
Q	2.60	—	3.20

TO-220F-3L

UNIT: mm



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	4.42	4.70	5.02
A1	2.30	2.54	2.80
A3	2.50	2.76	3.10
b	0.70	0.80	0.90
b2	—	—	1.47
c	0.35	0.50	0.65
D	15.25	15.87	16.25
D1	15.30	15.75	16.30
D2	9.30	9.80	10.30
E	9.73	10.16	10.36
e	2.54BSC		
H1	6.40	6.68	7.00
L	12.48	12.98	13.48
L1	—	—	3.50
φP	3.00	3.18	3.40
Q	3.05	3.30	3.55

Important notice :

- The instructions are subject to change without notice! Customers should obtain the latest relevant information before placing orders and should verify that such information is complete and current.
- Our products are consumer electronic products, and / or civil electronic products.
- When using our products, please do not exceed the maximum rating of the products, otherwise the reliability of the whole machine will be affected. There is a certain possibility of failure or malfunction of any semiconductor product under specific conditions. The buyer is responsible for complying with safety standards and taking safety measures when using our products for system design, sample and whole machine manufacturing, so as to avoid potential failure risk that may cause personal injury or property loss.
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- When exporting, using and reselling our products, buyer must comply with the international export control laws and regulations of China, the United States, the United Kingdom, the European Union and other countries & regions.
- Product promotion is endless, our company will wholeheartedly provide customers with better products!
- Website: <http://www.silan.com.cn>

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Rev.: **1.2**

Revision History:

1. Deleted NOMENCLATURE
 2. Modify Important notice
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Rev.: **1.1**

Revision History:

1. Modify the package information of TO-220F-3L
 2. Modify the package information of TO-220-3L
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Rev.: **1.0**

Revision History:

1. First release
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